

Claim 3 (Previously Presented): A semiconductor light-emitting element mounting member according to claim 1 wherein said metal film is formed as an alloy of at least one of Ag and Al and other metal, a proportional content of said other metal being 0.001 - 10 percent by weight.

Claim 4 (Original): A semiconductor light-emitting element mounting member according to claim 3 wherein said other metal is at least one type of metal selected from a group consisting of Cu, Mg, Si, Mn, Ti, and Cr.

Claim 5 (Canceled).

Claim 6 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein said metal film is formed from Al alone or from an alloy of Al and other metal.

Claim 7 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein a thermal expansion coefficient of said substrate is $1 \times 10^{-6}/K$ - $10 \times 10^{-6}/K$.

Claim 8 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein a thermal conductivity of said substrate is at least 80 W/mK.

Claim 9 (Original): A semiconductor light-emitting element mounting member according to claim 1 wherein said semiconductor light-emitting element mounting member is a flat submount.

Claim 10 (Currently Amended): A semiconductor light-emitting element mounting member of claim 1 further comprising ~~device wherein~~ a semiconductor light-emitting element is mounted thereto ~~in a semiconductor light-emitting element mounting member according to claim 1.~~

Claim 11 (Currently Amended): A semiconductor light-emitting device according to claim 10 wherein the output of said semiconductor light-emitting element is at least 1 W.